





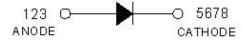
ST3050DJF SCHOTTKY RECTIFIER



Features

- Ultralow forward voltage drop
- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low thermal resistance
- Avalanche capability specified
- Thin package: 1 mm
- This is a Pb Free Device
- . All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- · Reverse battery protection

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	-	50	V
Average Rectified Forward Current	I _{F (AV)}	50% duty cycle @T _c =80°C, rectangular wave form	30	Α
Peak One Cycle Non-Repetitive Surge Current	I _{FSM}	8.3ms, Half Sine pulse, T _C = 25 °C	180	А

Electrical Characteristics:

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop*	V_{F1}	@ 15A, Pulse, T _J = 25 °C @ 30A, Pulse, T _J = 25 °C	0.47 0.56	0.55 0.65	V
	V _{F2}	@ 15A, Pulse, T _J = 125 °C @ 30A, Pulse, T _J = 125 °C	0.41 0.54	-	V
Reverse Current*	I _{R1}	$@V_R = \text{rated } V_R$ $T_J = 25 ^{\circ}\text{C}$	0.03	0.8	mA
Reverse Current*	I _{R2}	$@V_R = \text{rated } V_R$ $T_J = 125 ^{\circ}\text{C}$	17	60	mA
Junction Capacitance	Ст	$@V_R = 5V, T_C = 25 °C$ $f_{SIG} = 1MHz$	900	-	pF

Pulse width < 300 μs, duty cycle < 2%



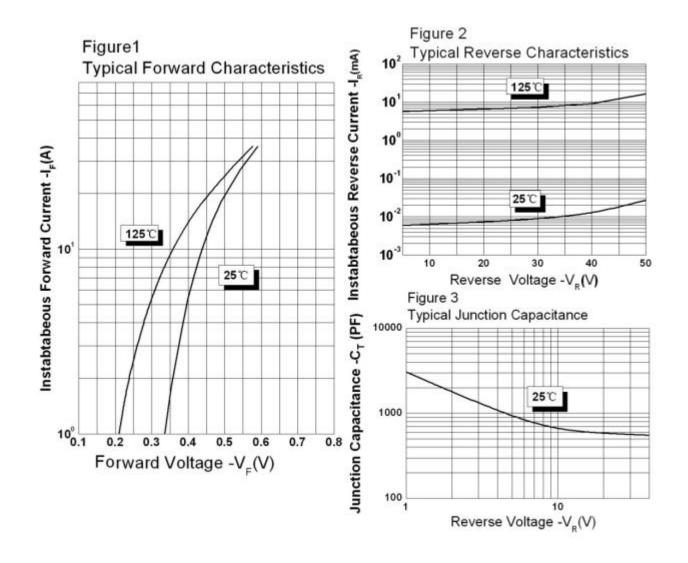




Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Max. Junction Temperature	T_J	-	150	°C
Storage Temperature	T_{stg}	-	-65 to + 175	°C
Typical Thermal Resistance Junction to Case	R₀Jc	DC operation	2.5	°C/W
Approximate Weight	wt	-	0.095	g

Ratings and Characteristics Curves



[•] China - Germany - Korea - Singapore - United States •

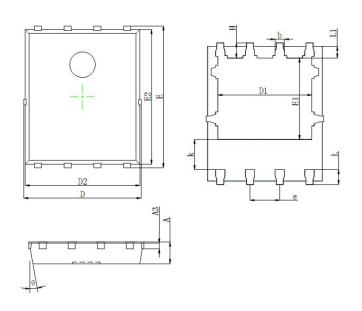
[•] http://www.smc-diodes.com - sales@ smc-diodes.com •





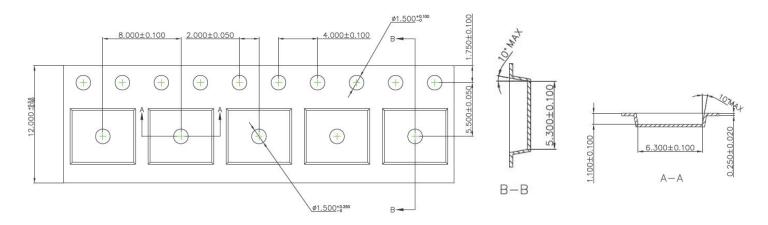


Mechanical Dimensions PDFNWB5×6-8L



SYMBOL	Millimeters		Inches	
STWIBOL	Min.	Max.	Min.	Max.
Α	0.900	1.000	0.035	0.039
A3	0.254 REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	5.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
е	1.270 TYP.		0.050 TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
Н	0.574	0.726	0.023	0.029
Θ	10°	12°	10°	12°

Carrier Tape Specification PDFNWB5×6-8L(mm)

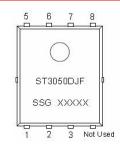


Ordering Information

Device	Package	Shipping
ST3050DJF	PDFNWB5×6-8L	3000 pcs / reel
0.000000	(Pb-Free)	0000 poo 7 1001

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

 ST
 = Device Type

 30
 = Forward Current (30A)

 50
 = Reverse Voltage (50V)

 DJF
 = Package type

 SSG
 = SSG

 YY
 = Year

 WW
 = Week

 L
 = Lot Number

Cautions: Molding resin Epoxy resin UL:94V-0

- China Germany Korea Singapore United States
 - http://www.smc-diodes.com sales@ smc-diodes.com •







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